

IN THE CLAIMS:

Claims 1-20 (canceled)

Claim 21 (currently amended): A semiconductor device, comprising:

a ~~solid-device~~ primary semiconductor chip;

a secondary semiconductor chip mounted and face-down-bonded onto a surface of the ~~solid-device~~ primary semiconductor chip to form a chip-on-chip structure;

a package that packages the chip-on-chip structure;

a functional bump formed on the surface of the primary semiconductor chip, for electrical connection between ~~an~~ internal circuits of the primary and secondary semiconductor chips ~~and the solid-device~~; and

a primary dummy bump, formed on the surface of the primary semiconductor chip, not serving for electrical connection between the internal circuits, the primary dummy bump having a height that is substantially equal to a height of the primary functional bump; ~~and the solid-device wherein at least one of the solid-device and the semiconductor chip includes a low impedance portion and the dummy bump is electrically connected to the low impedance portion,~~

~~wherein the~~ a secondary functional bump is disposed in association with a peripheral portion of a mating surface of the primary semiconductor chip opposed to the solid-device, primary semiconductor chip, for electrical connection between the internal circuits; and

~~wherein the~~ a secondary dummy bump₁ is disposed in association with a central portion of the mating surface, not serving for electrical connection between the internal circuits but serving for absorption of a force exerted on the secondary semiconductor chip, the secondary dummy bump having a height that

is substantially equal to a height of the secondary functional bump;

the primary and secondary functional bumps being joined to each other,
thereby electrically connecting the primary and secondary semiconductor chips,

the primary and secondary dummy bumps being joined to each other over
an area of contact extending over an entire active region of the mating surface of
the secondary semiconductor chip.

Claim 22 (currently amended): A The semiconductor device according to claim 21, wherein the area over which the primary and secondary dummy bumps ~~has a~~ are joined to each other ~~is greater contact area in contact with the solid device than~~ an area over which of the primary and secondary functional bumps are joined to each other.

Claims 23-31 (canceled).

Claim 32 (new): The semiconductor device according to claim 21, wherein at least one of the primary and secondary semiconductor chips includes a low impedance portion and the primary and secondary dummy bumps are electrically connected to the low impedance portion.